

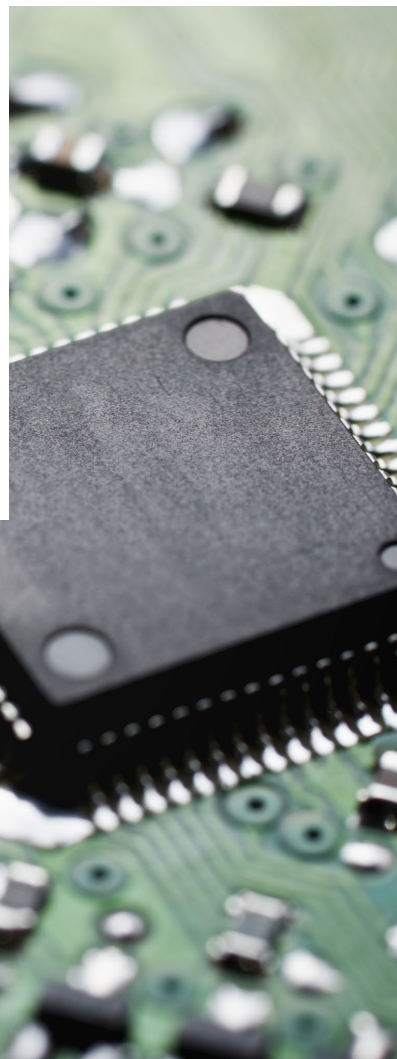
LOW POWER SRAMs

Advanced technology with superior performance
and industry-leading support



HIGH PERFORMANCE AND
HIGH RELIABILITY USING
RENESAS'S ORIGINAL TECHNOLOGY

LOW POWER SRAMs



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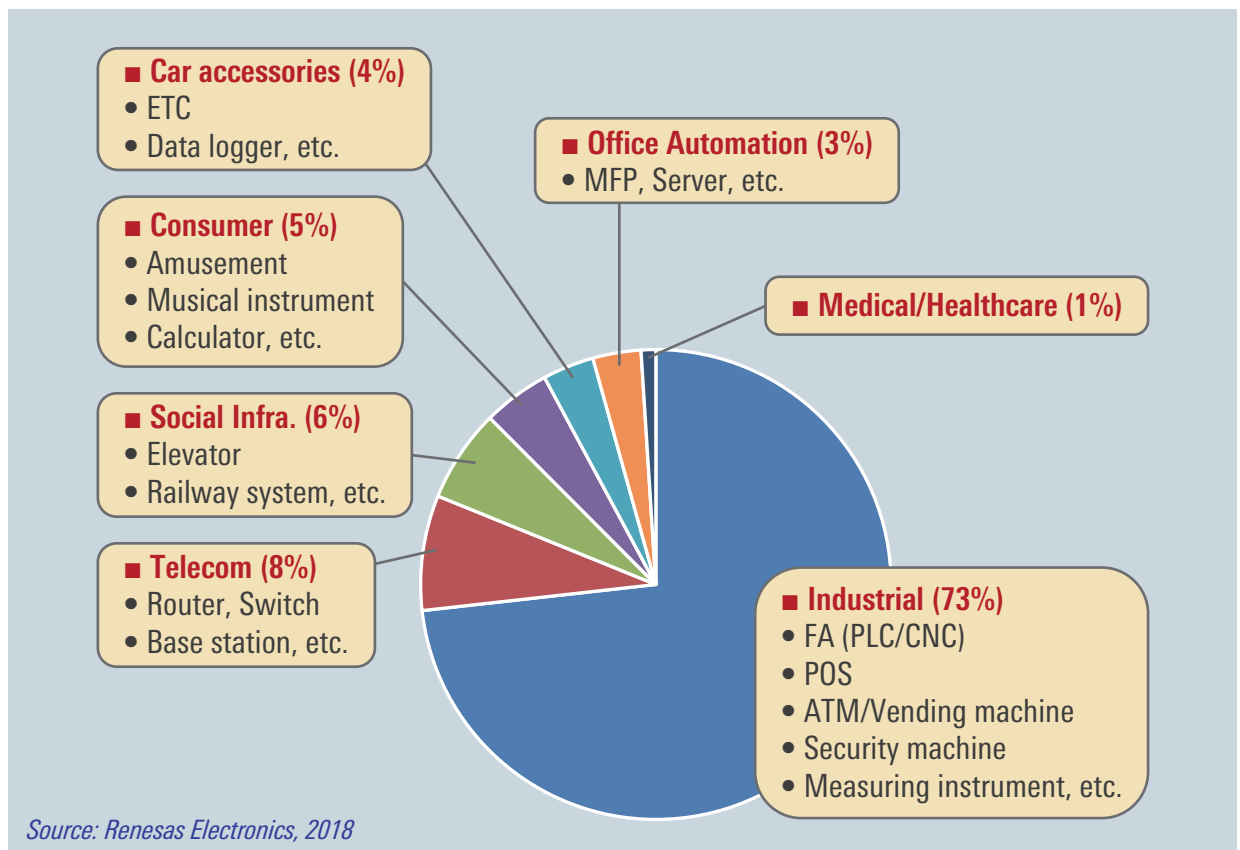
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Low Power SRAM Roadmap

SRAM type	Density, Voltage						
		CY2018	2019	2020	2021	MP	New
Low Power SRAM	256Kb 5V/3V, 1Mb 5V/3V, 2Mb 3V, 4Mb 5V	0.15μm Advanced LPSRAM					
	4Mb 3V, 8Mb 3V, 16Mb 3V, 32Mb 3V(16Mb x2)	0.11μm Advanced LPSRAM					
	16Mb 3V	0.13μm CMOS (ECC embedded)					
	32Mb 3V	0.15μm	0.11μm Advanced LPSRAM				
	64Mb 3V	0.15μm	0.11μm Advanced LPSRAM				

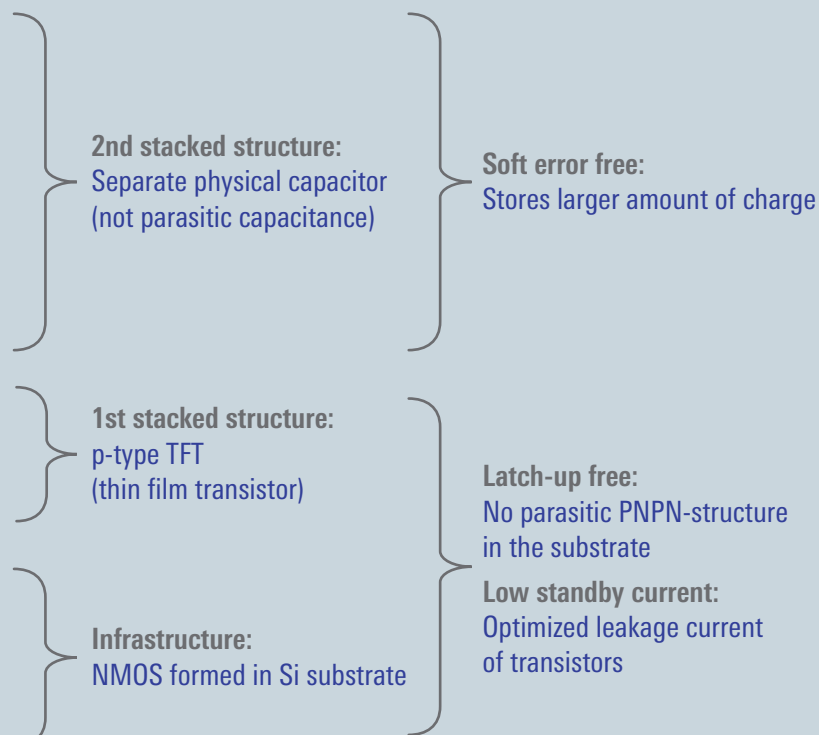
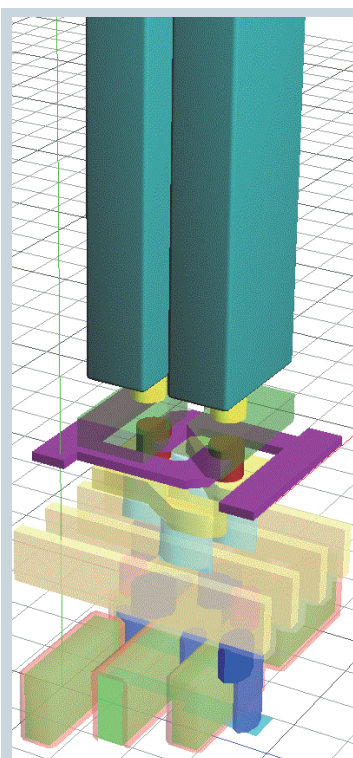
- Widest product lineup from 256Kbit to 64Mbit
- Long term and stable support
- Highest quality with Renesas core advanced technology
- Easy switch to higher density in the same package

Industry-Leading Support, Application of Renesas Low Power SRAM



Advanced Low Power SRAM Technology with Superior Performance and Reliability

- Low standby current
- High reliability
 - Soft error free
 - Latch-up free



Renesas' Advanced LPSRAM Technology: 3D Image of Memory Cell

Product Differentiation

Renesas supports soft error free products for entire lineup of 256Kbit to 64Mbit

✓ Production Soft error countermeasure: **Yes** **No**

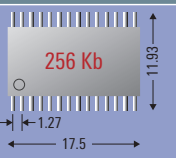
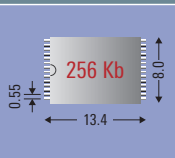
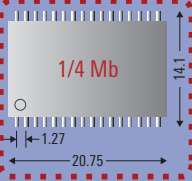
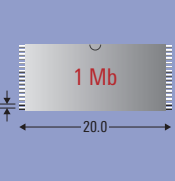
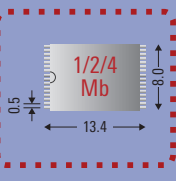
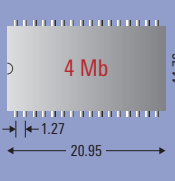
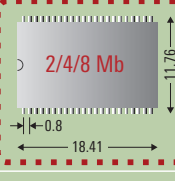
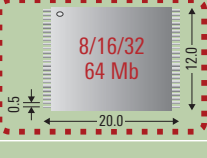
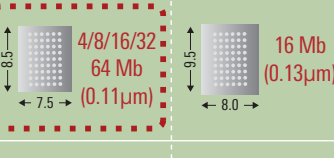
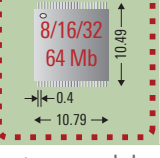
Vendor	Process	256Kb	1Mb	2Mb	4Mb	8Mb	16Mb	32Mb	64Mb
Renesas	0.13μm CMOS ECC embedded						✓		
	0.15μm Advanced	✓	✓	✓	✓ (5V)	Change to 0.11μm Advanced			✓
	0.11μm Advanced				✓ (3V)	✓	✓	✓	Development
Competitor	90nm CMOS no ECC	✓	✓	✓	✓	✓	✓	✓	✓
	65nm CMOS ECC embedded				✓	✓	✓	Development	Development

Product Benchmark

Only Renesas supports unique products that realize both lowest standby current and soft error free

vs.	Renesas 0.11μm Advanced LPSRAM	Competitor's 65nm LPSRAM (with ECC)
Standby current	0.5μA (16Mb, typ.)	5.5μA (16Mb, typ.)
vs.	Renesas 0.11μm Advanced LPSRAM	Competitor's 90nm LPSRAM (no ECC)
Soft error rate	< 0.1 FIT / Mbit	500 to 1,000 FIT / Mbit

Package Lineup for Low Power SRAM

	SOP	TSOP-I	sTSOP	TSOP-II	μTSOP	FBGA
28-pin						
32-pin						
44-pin						
48-pin (48-ball)						
52-pin						

x8
config. ↑
x8 / x16
config. ↓

■ Renesas provides 6 kinds of common packages, which are upward compatible, making it easy to expand density without changing the PCB.

Low Power SRAM Part Name Decoder

R1 L V 5256 E SA - 5 S I #B1
R1 L P 04 08 D SP - 5 S I #B0
RM L V 04 16 E G SB - 4 S 2 #A A 1

Renesas Memory
Chip Configuration
L LPSRAM, Single chip
W LPSRAM, Two chips

Operating Voltage
V 3V
P 5V

Memory Density

5256	256Kb (x8)
01	1Mb
02	2Mb
04	4Mb
08	8Mb
16	16Mb
32	32Mb
64	64Mb

Bus Width
08 x8
16 x16

Chip Generation
Industrial Grade

Package Type

SA	TSOP-I (256Kb/8Mb/16Mb/32Mb/64Mb)
SB	TSOP-II (1Mb/2Mb/4Mb)
SD	μTSOP
SF	TSOP-I (1Mb)
SP	SOP (256Kb, 4Mb)
SN	SOP (1Mb)
BG	FBGA

Packing, Environmental

	Packing	Environmental
#B0 / #B1	Tray or Tube	Pb free
#S0 / #S1	Embossed Tape	Pb free

Environment

A	Pb free (pure-Tin plating)
C	Pb free (non pure-Tin plating)

Operating Temperature

R	0 to 70°C
I	-40 to 85°C
2	-40 to 85°C

Packing

A	Tray
C	Tube
H	Embossed Tape (TSOP, μTSOP, SOP)
K	Embossed Tape (FBGA, sTSOP)

Access Time

5	55 ns
4	45 ns

Standby Current / Data Retention Current

L	Standard
S	Low power version

Assembly Site Rev., etc.

0	Rev. Code
1	Rev. Code

Product List

Process	Density	Configuration	Part Name	Package	Access Time	Voltage	Temperature
0.15μm Advanced	256Kbit	32K x 8	R1LP5256ESP	SOP (28)	55ns	4.5V to 5.5V	-40 to 85°C
			R1LP5256ESA	TSOP-I (28)	55ns	4.5V to 5.5V	-40 to 85°C
			R1LV5256ESP	SOP (28)	55ns	2.7V to 3.6V	-40 to 85°C
			R1LV5256ESA	TSOP-I (28)	55ns	2.7V to 3.6V	-40 to 85°C
0.15μm Advanced	1Mbit	128K x 8	R1LP0108ESN	SOP (32)	55ns	4.5V to 5.5V	-40 to 85°C
			R1LP0108ESF	TSOP-I (32)	55ns	4.5V to 5.5V	-40 to 85°C
			R1LP0108ESA	sTSOP (32)	55ns	4.5V to 5.5V	-40 to 85°C
			R1LV0108ESN	SOP (32)	55ns	2.7V to 3.6V	-40 to 85°C
			R1LV0108ESF	TSOP-I (32)	55ns	2.7V to 3.6V	-40 to 85°C
			R1LV0108ESA	sTSOP (32)	55ns	2.7V to 3.6V	-40 to 85°C
0.15μm Advanced	2Mbit	256K x 8	R1LV0208BSA	sTSOP (32)	55ns	2.7V to 3.6V	-40 to 85°C
		128K x 16	R1LV0216BSB	TSOP-II (44)	55ns	2.7V to 3.6V	-40 to 85°C
0.15μm Advanced	4Mbit	512K x 8	R1LP0408DSP	SOP (32)	55ns	4.5V to 5.5V	-40 to 85°C
			R1LP0408DSB	TSOP-II (32)	55ns	4.5V to 5.5V	-40 to 85°C
0.11μm Advanced	4Mbit	512K x 8	RMLV0408EGSP	SOP (32)	45ns	2.7V to 3.6V	-40 to 85°C
			RMLV0408EGSB	TSOP-II (32)	45ns	2.7V to 3.6V	-40 to 85°C
			RMLV0408EGSA	sTSOP (32)	45ns	2.7V to 3.6V	-40 to 85°C
		256K x 16	RMLV0414EGSB	TSOP-II (44)	45ns	2.7V to 3.6V	-40 to 85°C
			RMLV0416EGSB	TSOP-II (44)	45ns	2.7V to 3.6V	-40 to 85°C
			RMLV0416EBGB	FBGA (48)	45ns	2.7V to 3.6V	-40 to 85°C
0.11μm Advanced	8Mbit	1M x 8	RMLV0808BGSB	TSOP-II (44)	45ns	2.7V to 3.6V	-40 to 85°C
					55ns	2.4V to 3.6V	-40 to 85°C
		512K x 16	RMLV0816BGSB	TSOP-II (44)	45ns	2.7V to 3.6V	-40 to 85°C
					55ns	2.4V to 3.6V	-40 to 85°C
			RMLV0816BGBG	FBGA (48)	45ns	2.7V to 3.6V	-40 to 85°C
					55ns	2.4V to 3.6V	-40 to 85°C
		512K x 16 / 1M x 8	RMLV0816BGSA	TSOP-I (48)	45ns	2.7V to 3.6V	-40 to 85°C
					55ns	2.4V to 3.6V	-40 to 85°C
			RMLV0816BGSD	μTSOP (52)	45ns	2.7V to 3.6V	-40 to 85°C
					55ns	2.4V to 3.6V	-40 to 85°C
0.13μm CMOS	16Mbit (with ECC)	1M x 16 / 2M x 8	R1LV1616HSA	TSOP-I (48)	45ns	2.7V to 3.6V	-40 to 85°C
		1M x 16	R1LV1616HBG	FBGA (48)	45ns	2.7V to 3.6V	-40 to 85°C
0.11μm Advanced	16Mbit	1M x 16 / 2M x 8	RMLV1616AGSA	TSOP-I (48)	55ns	2.7V to 3.6V	-40 to 85°C
			RMLV1616AGSD	μTSOP (52)	55ns	2.7V to 3.6V	-40 to 85°C
		1M x 16	RMLV1616AGBG	FBGA (48)	55ns	2.7V to 3.6V	-40 to 85°C
0.11μm Advanced	32Mbit	2M x 16 / 4M x 8	RMLV3216AGSA	TSOP-I (48)	55ns	2.7V to 3.6V	-40 to 85°C
			RMLV3216AGSD	μTSOP (52)	55ns	2.7V to 3.6V	-40 to 85°C
		2M x 16	RMLV3216AGBG	FBGA (48)	55ns	2.7V to 3.6V	-40 to 85°C
0.11μm Advanced	32Mbit	2M x 16	RMWV3216AGBG	FBGA (48)	55ns	2.7V to 3.6V	-40 to 85°C
0.11μm Advanced	64Mbit	4M x 16 / 8M x 8	RMWV6416AGSA	TSOP-I (48)	55ns	2.7V to 3.6V	-40 to 85°C
			RMWV6416AGSD	μTSOP (52)	55ns	2.7V to 3.6V	-40 to 85°C
		4M x 16	RMWV6416AGBG	FBGA (48)	55ns	2.7V to 3.6V	-40 to 85°C

MEMO

This image shows a full page of a handwriting practice worksheet. It consists of multiple sets of three horizontal dashed lines spaced evenly down the page, providing a guide for letter height and placement. The background is plain white, and there are no other markings or text present.

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